

**SERIES 6200MP NON FOULING
SUBMERSIBLE LEVEL SENSOR****FEATURES**

- Continuous Output
- Non Fouling Flush Diaphragm Design
- For Sludge & Sewage Applications
- 316SS Construction
- Viton Diaphragm
- Microprocessor Based Electronics
- Ultra Stable/High 0.2% Accuracy
- 4/20MA and/or MODBUS® Outputs
- Ranges to 70 Feet Water Plus
- No Desiccants or Breather Tubes
- Fully Repairable & Field Calibrateable

CONSTRUCTION

The Series 6200MP Microprocessor Based Level System is composed of a lower assembly sensor, submersible cable and optional meter/controller. The lower assembly sensor has a 316SS body, a 1.25 inch diameter Viton* diaphragm and an isolated solid state piezo-resistive pressure transducer. The integral microprocessor based electronics provide active temperature compensation and significantly improved performance while offering a range of outputs including 4/20MA and MODBUS®.

The submersible cable is 20-gauge direct burial polyurethane jacket shielded cable available in unspliced lengths to 1000 feet.

Mounted in a fixed submerged position, the Series 6200MP sensor measures the head pressure imposed

on the diaphragm by the liquid height above. Calibrated to the specific gravity of the process fluid, the sensor operates reliably in clear and wastewater wet wells as well as sludge and process sumps, tanks and reservoirs. The 6200MP sensor is an excellent choice for measuring levels of dense sludges since it provides reliable data without the complexity and clogging often associated with other types of systems.

The straight-forward design and construction of the 6200MP sensor recommends it for use in water, wastewater and process applications whenever an analog signal is required for pump control, indication, alarm or telemetry applications.

**MOUNTING & PROCESS
MEDIA REQUIREMENTS**

The 6200MP sensor can be either pipe suspended (1/2 inch NPT) or

cable-suspended in a vertical position in the reservoir or well to be monitored. The process media can be any type compatible with the sensor and cable materials (316SS, Viton,* polyurethane).

**SOLID STATE
PRESSURE SENSOR**

The sensing element of the solid state pressure sensor consists of four nearly identical piezo-resistors buried in the surface of a thin circular silicon diaphragm. Gold pads attached to the silicon chip surface provide connection to the piezo-resistors and serve as pads for bonding of the wire leads. A pressure causes the thin diaphragm to flex, inducing a stress or strain in the diaphragm and also in the buried resistors. Therefore, a change in pressure (mechanical input) is converted to a change in resistance (electric output).

